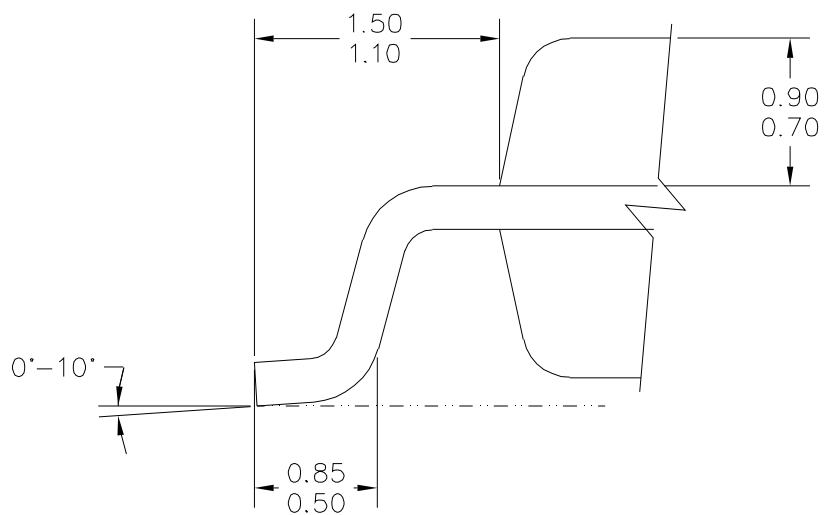
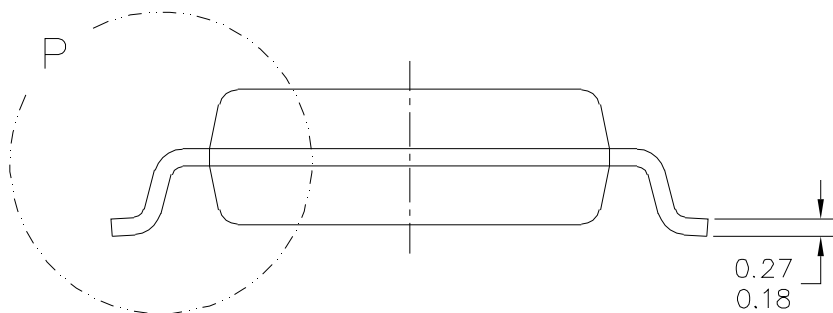


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DETAIL P



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NOTES:

1. DIMENSIONS AND TOLERANCES PER ASME Y14.5–1994.

2. CONTROLLING DIMENSION: MILLIMETER.

3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15mm PER SIDE.

4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

5. THE LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46mm.

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